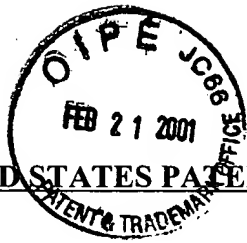


S/N 09/259,849



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Paul A. Farrar

Examiner: Bernard E. Souw

Serial No.: 09/259,849

Group Art Unit: 2814

Filed: March 1, 1999

Docket: 303.557US1

Title: CONDUCTIVE STRUCTURES IN INTEGRATED CIRCUITS

#11/a
3/23/01
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AMENDMENT AND RESPONSE UNDER 37 C.F.R. § 1.111

Commissioner for Patents
Washington, D.C. 20231

Applicant has reviewed the Office action mailed on September 28, 2000.

This response is accompanied by a petition, as well as the appropriate fee, to obtain a two-month extension of the time period for responding to the Office action, thereby moving the deadline for response from December 28, 2000 to February 28, 2000.

Please amend the above-identified patent application as follows.

IN THE CLAIMS

Please amend the claims as follows:

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50. [Amended] A method of forming a conductor comprising:
depositing an oxide layer over a planarized surface;
etching a trench on the oxide layer;
depositing a barrier layer of titanium on the oxide layer;
depositing a seed layer of aluminum-copper on the barrier layer [oxide layer];
removing the barrier layer and seed layer from selected areas or unused areas of the oxide layer, leaving a seed area; and
depositing aluminum on the seed area.

54. [Amended] The method of claim 50, wherein depositing a seed layer of aluminum-copper [titanium] on the barrier layer [oxide layer] comprises:
depositing the seed layer of aluminum-copper [titanium] on the barrier [oxide] layer by chemical vapor-deposition.